

HY991101C

Electrical Specification @25°C

RoHS Compliant

Operating Temperature Range: 0°C ~ +70°C

Isolation: 2250Vdc 0.5mA 60Sec (UTP Side to Chip Side)

OCL: 350uH Minimum @100KHz 100mV with 8mADC

Insertion Loss: -1.0dB Maximum @1MHz ~ 65MHz

Return Loss: -18dB Minimum @1MHz ~ 10MHz

-14dB Minimum @30MHz

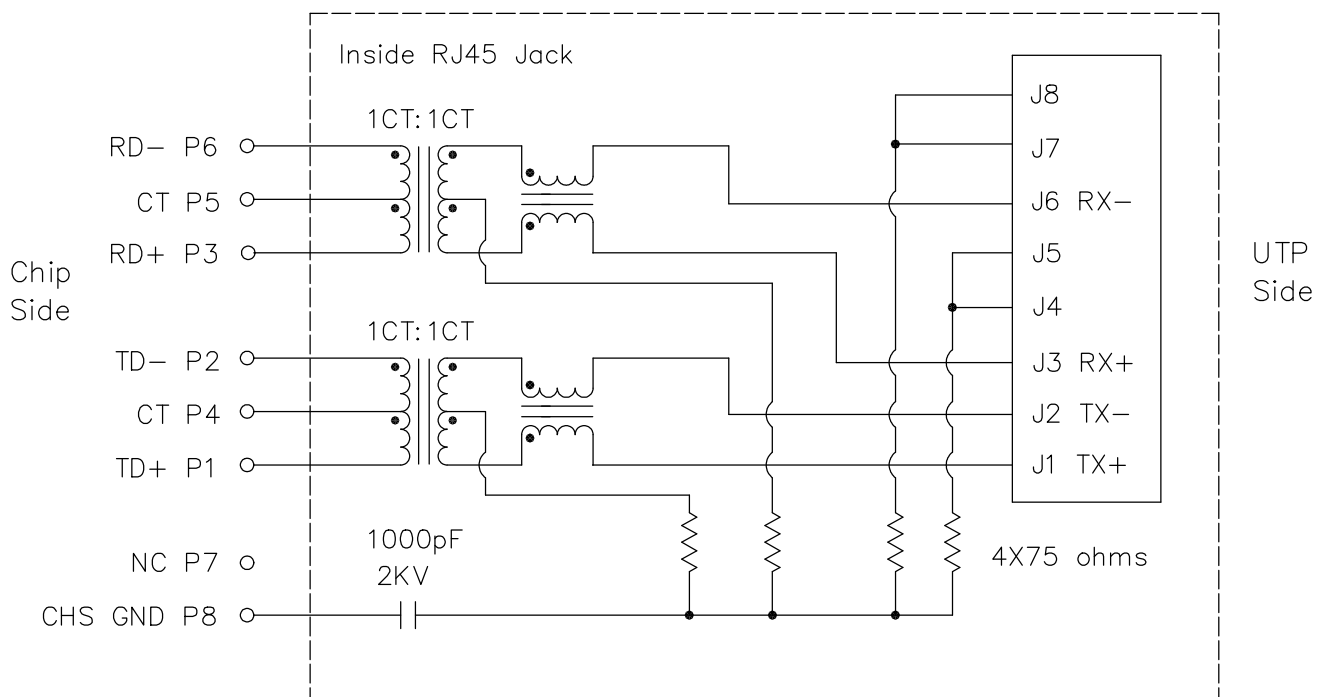
-10dB Minimum @60MHz ~ 80MHz

Common Mode Rejection: -20dB Minimum @1MHz ~ 130MHz

Crosstalk: -35dB Minimum @1MHz ~ 60MHz

-30dB Minimum @60MHz ~ 100MHz

Schematics

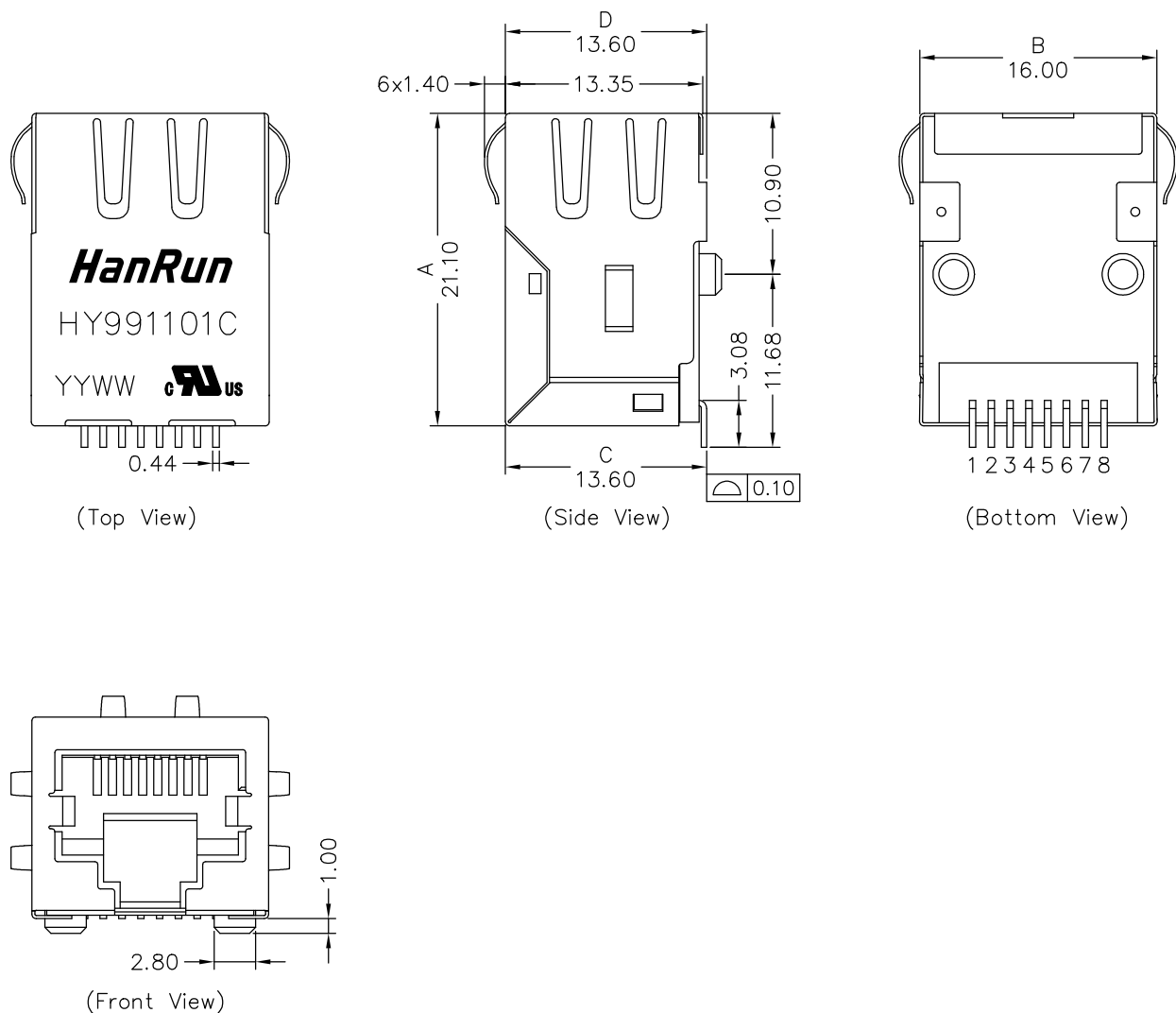


Notes: Connect CHS GND to PCB Ground

HY991101C

- RoHS Compliant
- Meets or Exceeds IEEE802.3 standards including 350uH Min OCL with 8mADC
- High performance for EMI suppression, Crosstalk, Return Loss and Consistent Electrical
- Minimum 2250VDC isolation per IEEE802.3 requirement
- Minimize PCB space and Simplify PCB Layout
- Less magnetic components to be placed on PCB, higher reliability and yields
- UL Recognized Component: File # E330599

Mechanical Dimensions:



Dimensions in mm

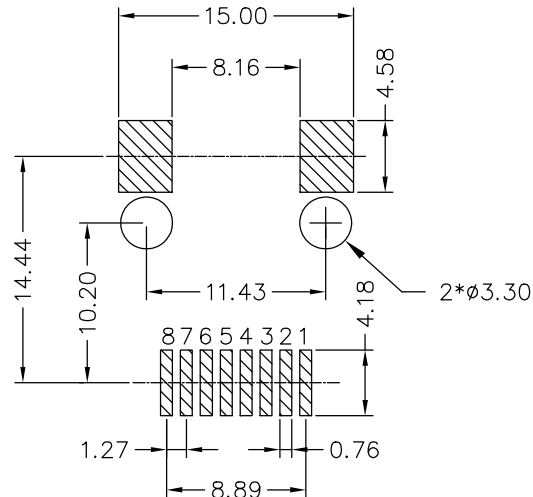
Unless otherwise specified, Tolerance: .xx ±0.25

REV.: B0

2 of 4

HY991101C

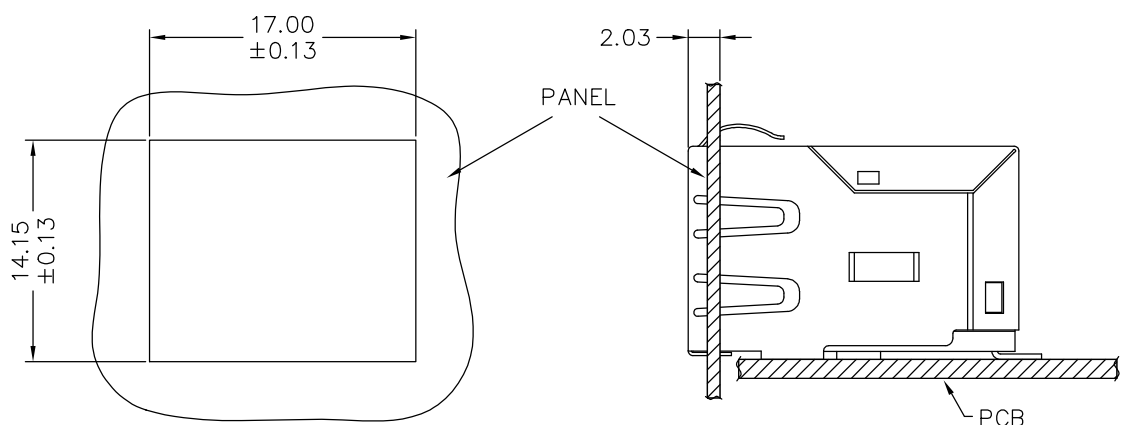
Mechanical Dimensions:



(Component Side View)
(Mounting Pattern)

Recommended PCB layout (Component Side View)
All dimension tolerance are ± 0.08 unless otherwise specified

Suggested Panel Cutout:



SUGGESTED PANEL OPENING

Dimensions in mm

Unless otherwise specified, Tolerance: .xx ± 0.25

REV.: B0

3 of 4

HY991101C

Material Specification:

Housing: PA9T GF Black UL94V-0
Shield: 30u" Nickel over 0.20mm Thickness Brass
Insert: PA9T GF Black UL94V-0
Phosphor Bronze 0.35mm Thickness
Plating Area, 30u" gold over 50u" nickel
Solder Area, 100u" tin over 50u" nickel

Mechanical Performance:

Mating force: 5 lbs Maximum
Unmating force: 5 lbs Maximum
Plug to Jack Retention force: 12 lbs Minimum
Operating life: 750 Cycles Minimum

Operating and Storage Temperature:

Operating Temperature Range: 0°C ~ +70°C
Storage Temperature Range: -40°C ~ +85°C